

Technical Data Sheet

MODEL NO: S776ANB4-P

3528 Package 3.5*2.8mm Top LEDs

Features:

• Package in 8mm tape on 7" diameter reel

• Compatible with automatic placement equipment

• Compatible with reflow solder process

Applications:

Indicators

• Automotive: backlighting in dashboard and switch

Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN	Blue	Water Clear

Electrical/Optical Characteristics(Ta= 25° C)

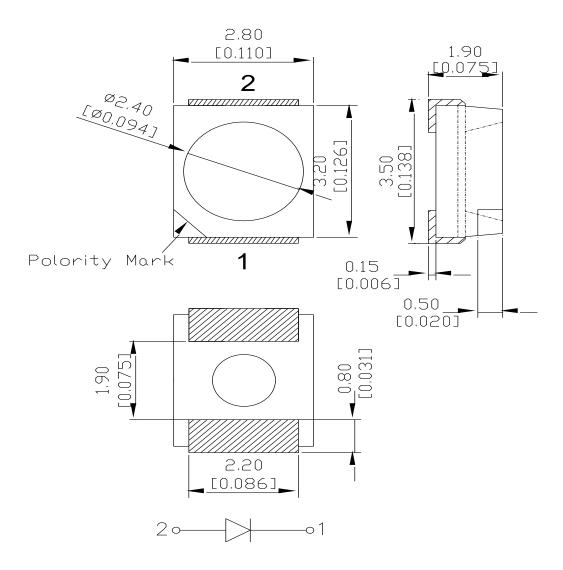
Parameter	Test	Symbol	Value			Unit
	Condition		Min	Тур	Max	Unit
Dominant wavelength	I=20mA	λD		465	470	nm
Forward voltage	I=20mA	VF	3.0		3.4	٧
Luminous intensity	I=20mA	lv	400		500	mcd
Viewing angle at 50% lv	I=10mA	20 1/2		120		Deg
Reverse current	V _R =5V	lr			10	μΑ

Absolute Maximum Ratings(Ta= 25° C)

Parameter	Symbol	Value	Unit
Power dissipation	Pd	60	mW
Forward current	lf	20	mA
Reverse voltage	VR	5	V
Operating temperature range	Тор	-20 ~+80	$^{\circ}\!\mathbb{C}$
Storage temperature range	Tstg	-40 ~+80	$^{\circ}\!\mathbb{C}$
Peak pulsing current (1/10 duty f=1kHz)	lfp	20	mA



PACKAGING DIMENSIONS (mm):

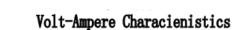


Notes: All dimensions are in millimeters (inches);

Tolerances are ± 0.2 mm(0.008inch) unless otherwise noted

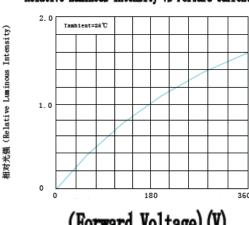


(Optical-Electrical Characteristic)



正向电流 (Forward Current) (mA) 360 270 90 (Forward Voltage) (V)

Relative Luminous Intensity VS Forward Current

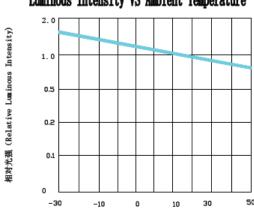


(Forward Voltage) (V)

Forward Current Derating Curve



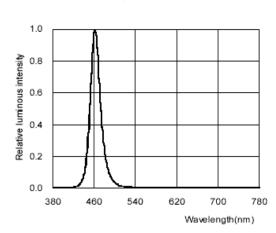
Luminous Intensity VS Ambient Temperature



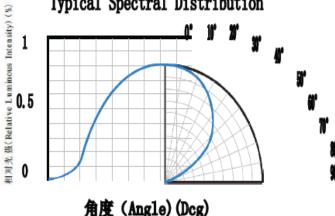
(Ambient Temperature) (C)

(Ambient Temperature) (C)

Relative spectral emission



Typical Spectral Distribution



Precautions For Use:

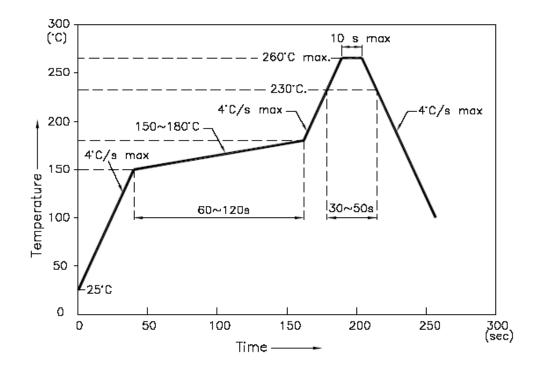
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

- 1. We recommend the reflow temperature $245\,^{\circ}\text{C}(\pm 5\,^{\circ}\text{C})$.the maximum soldering temperature should be limited to $260\,^{\circ}\text{C}$.
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

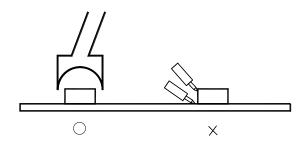


■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.